

**N-Ch MOSFET** 

## **General Description**

The WSR130N06 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in

#### **Features**

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

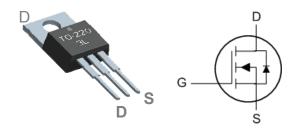
## **Product Summery**

BVDSS	RDSON	ID		
60V	$3.0 m\Omega$	130A		

## **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

#### **TO-220AB Pin Configuration**



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	60	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	130	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	390	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	80	mJ	
P <sub>D</sub> @T <sub>C</sub> =25℃	P <sub>D</sub> @T <sub>C</sub> =25℃ Total Power Dissipation <sup>4</sup>		W	
T <sub>J</sub> T <sub>STG</sub>	Γ <sub>J</sub> T <sub>STG</sub> Operating Junction Temperature Range -55 to 175		$^{\circ}$	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
R <sub>0JC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		0.89	°C/W



#### Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS}$ =10V , $I_D$ =20A		3.0	3.5	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS}$ =4.5 $V$ , $I_D$ =10 $A$		3.5	4.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1.0		2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =48V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
$Q_g$	Total Gate Charge			36		
$Q_{gs}$	Gate-Source Charge	$V_{DS}$ =30V , $V_{GS}$ =10V , $I_{D}$ =25A		9.9		nC
$Q_{gd}$	Gate-Drain Charge			6.6		
$T_{d(on)}$	Turn-On Delay Time	V <sub>DS</sub> =30V , V <sub>GS</sub> =10V ,		16		
T <sub>r</sub>	Rise Time	$I_D=25A$ , $R=2\Omega$ .		10		no
$T_{d(off)}$	Turn-Off Delay Time			45		ns
T <sub>f</sub>	Fall Time			12		
C <sub>iss</sub>	Input Capacitance			5377		
Coss	Output Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		1666		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			77.7		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			130	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time			68.3		nS
Q <sub>rr</sub>	Reverse Recovery Charge	IF=25A ,dl/dt=100A/µs,TJ=25˚C		73.0		nC

- ${\bf 1}, \ \ {\bf Calculated\ continuous\ current\ based\ on\ maximum\ allowable\ junction\ temperature}.$
- 2、Repetitive rating; pulse width limited by max. junction temperature.
- 3、Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a$ =25 °C.
- 5、 $V_{DD}$ =50 V,  $R_G$ =25  $\Omega$ , L=0.3 mH, starting  $T_j$ =25  $^{\circ}$ C.



#### **Typical Characteristics**

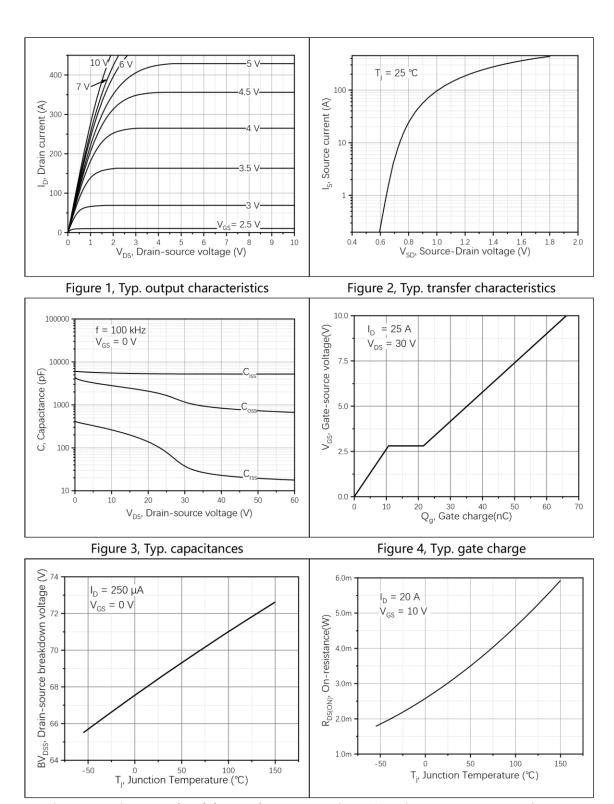
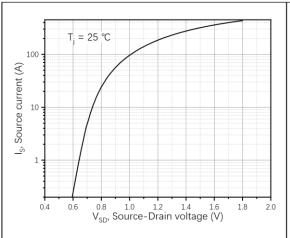


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance





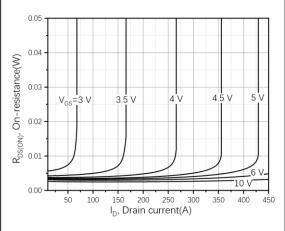


Figure 7, Forward characteristic of body diode

Figure 8, Drain-source on-state resistance

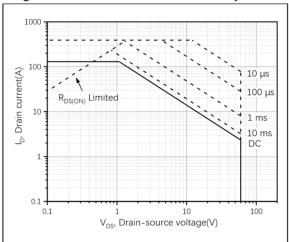


Figure 9, Safe operation area  $T_C=25\,^{\circ}C$ 



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